Docket No.: 062807-0453

To the Director of the U.S. Patent and Trademark Office

1. Name of Conveying Party(ies)
   Takumichi SUTANI, Ryoichi Matsuoka, Hidetoshi MOROKUMA, Akiyuki SUGIYAMA, Hiroyuki SHINDO

Additional name(s) of conveying party(ies) attached? □ Yes □ No

3. Nature of Conveyance/Execution Date(s)
   Execution Date(s): August 23, 2007; August 7, 2007; August 1, 2007; August 8, 2007; and August 23, 2007
   □ Assignment □ Merger
   □ Security Agreement □ Change of Name
   □ Joint Research Agreement □ Government Interest Assignment
   □ Executive Order 9424, Confirmatory License □ Other

Additional name(s) & address(es) attached? □ Yes □ No

4. Application or patent number(s):
   A. Application No. 11/892,675, filed on August 24, 2007
   Additional numbers attached? □ Yes □ No

5. Name and address to whom correspondence concerning document should be mailed:
   Name: MCDERMOTT WILL & EMERY LLP
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6. Total number of applications and patents involved:

7. Total fee (37 CFR 1.21(h) & 3.41) $40.00
   □ Authorized to be charged by credit card □ Authorized to be charged to deposit account
   □ Enclosed □ None required (government interest not affecting title)

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9. Signature.
   Keith E. George 34,111
   Name and Registration No. of Person Signing
   Signature
   Date May 22, 2008

Total number of pages including cover sheet, attachments and documents: 2
ASSIGNMENT
（譲渡証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 24-14, Nishishinbashishi 1-chome, Minato-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

PATTERN DISPLACEMENT MEASURING METHOD AND PATTERN MEASURING DEVICE

invented by me (if only one is named below ) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)
（発明者フルネームサイン）

1) Takumichi SUTANI 8/23/2007
2) Ryoichi MATANOSA 8/17/07
3) Hidetoshi MOROKUMA 8/1/07
6) 
7) 
8) 
9) 
10) 

Date Signed
（署名日）

RECORDED: 05/22/2008

PATENT
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